




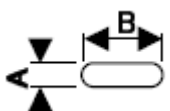




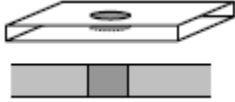





## Design Guide:

Part	Item	Explanation	Grade		
			Standard	Semi-Prem.	Premium
Conductor	Line width		$\geq 0.3\text{mm}$	$\geq 0.2\text{mm}$	$\geq 0.1\text{mm}$
	Line space		$\geq 0.3\text{mm}$	$\geq 0.2\text{mm}$	$\geq 0.1\text{mm}$
	Subs edge to pattern edge		$\geq 0.5\text{mm}$	$\geq 0.4\text{mm}$	$\geq 0.3\text{mm}$
	T/hole land		$\geq 0.35\text{mm}$	$\geq 0.3\text{mm}$	$\geq 0.25\text{mm}$
Hole	T/hole dia.		$\geq 0.5\text{mm}$	$\geq 0.4\text{mm}$	$\geq 0.3\text{mm}$
	T/hole dia.		A	$\geq 0.5\text{mm}$	$\geq 0.4\text{mm}$
			B	$\geq 0.6\text{mm} \sim$	$\geq 0.5 \sim 0.6\text{mm}$
	Hole to hole pitch		$\geq$ Substrate thickness		
	Subs edge to pattern edge		$\geq$ Substrate thickness		
Multilayer Print	Print Tolerance		$\geq 0.2\text{mm}$	$\geq 0.15\text{mm}$	$\geq 0.1\text{mm}$
	Subs edge to pattern edge		$\geq 0.5\text{mm}$	$\geq 0.4\text{mm}$	$\geq 0.3\text{mm}$

Part	Item	Explanation	Grade		
			Standard	Semi-Prem.	Premium
Special Shape	Via filling		$\Phi$ 0.4mm	$\Phi$ 0.3mm	$\Phi$ 0.2mm
			For land dia., to be discussed		
	T/hole print		To be discussed		
	Subs. 凸凹 shape				
	Print on 凸凹 part				
	T/hole print on 凸凹 area	